



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

Datum:

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PRINTED CIRCUIT BOARDS

01

4.11.2001

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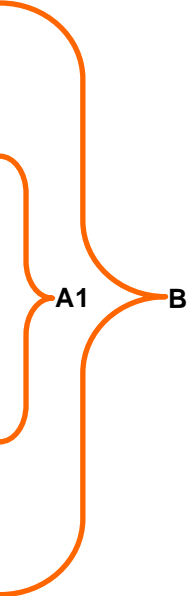


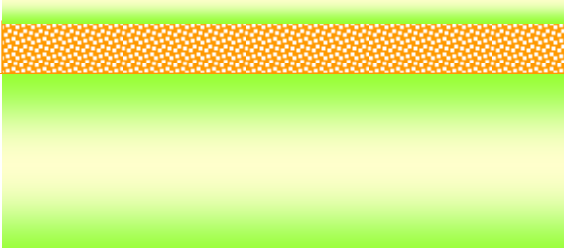




Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 247 FR4 55 L150.70 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_247_FR4_55_L150.70_p18

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	55 μ	Copper			
	180 μ	Prepreg			(180 μ PrePreg-Type: 7628)
	180 μ	Prepreg			
Layer-2	70 μ	Copper			
	1500 μ	L-FR4			
Layer-3	70 μ	Copper			
	180 μ	Prepreg			
	180 μ	Prepreg			
Layer-99	55 μ	Copper			

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